

Title (en)

Copper alloy sheet for electronic parts

Title (de)

Bleche aus Kupferlegierung für Elektronikbauteile

Title (fr)

Feuillard en alliage de cuivre pour composants électroniques

Publication

EP 0949343 A1 19991013 (EN)

Application

EP 99400634 A 19990315

Priority

- JP 26755798 A 19980922
- JP 10000798 A 19980326

Abstract (en)

A copper alloy sheet comprises 0.4 to 2.5 wt% of Ni, 0.05 to 0.6 wt% of Si, 0.001 to 0.05 wt% of Mg, and the balance being Cu and inevitable impurities wherein an average grain size in the sheet is in the range of 3 to 20 μm and a size of an intermetallic compound precipitate of Ni and Si is in the range of 0.3 μm or below. If necessary, the sheet may further comprise one or more of 0.01 to 5 wt% of Zn, 0.01 to 0.3 wt% of Sn, 0.01 to 0.1 wt% of Mn, and 0.001 to 0.1 wt% of Cr. It is preferred that when an X-ray diffraction intensity from $\{200\}$ plane in the surface of said sheet is taken as I_{200} , an X-ray diffraction intensity from $\{311\}$ plane is taken as I_{311} , and an X-ray diffraction intensity from $\{220\}$ plane is taken as I_{220} , the following equation is satisfied <MATH>

IPC 1-7

C22C 9/06

IPC 8 full level

H01L 23/48 (2006.01); **C22C 9/04** (2006.01); **C22C 9/06** (2006.01); **C22F 1/00** (2006.01); **C22F 1/08** (2006.01); **H01H 9/02** (2006.01)

CPC (source: EP KR US)

C22C 9/06 (2013.01 - EP KR US)

Citation (search report)

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- [X] DE 4319249 A1 19931216 - MITSUBISHI SHINDO KK [JP]
- [A] US 4594221 A 19860610 - CARON RONALD N [US], et al
- [X] PATENT ABSTRACTS OF JAPAN vol. 16, no. 560 (C - 1008) 2 December 1992 (1992-12-02)
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- [X] PATENT ABSTRACTS OF JAPAN vol. 16, no. 234 (C - 945) 29 May 1992 (1992-05-29)
- [A] PATENT ABSTRACTS OF JAPAN vol. 13, no. 182 (C - 591) 27 April 1989 (1989-04-27)

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